



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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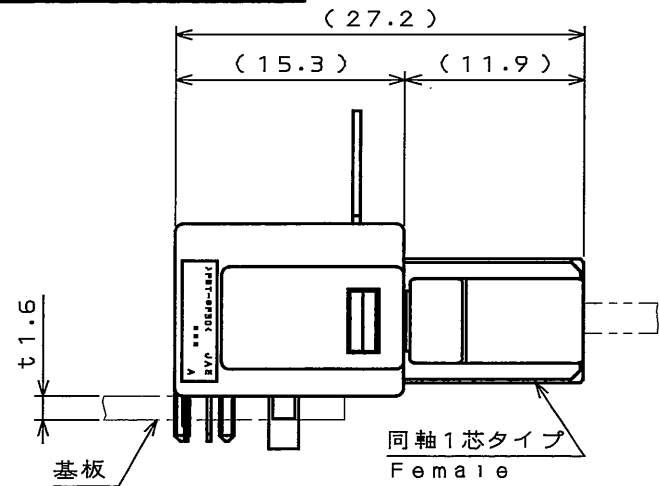
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



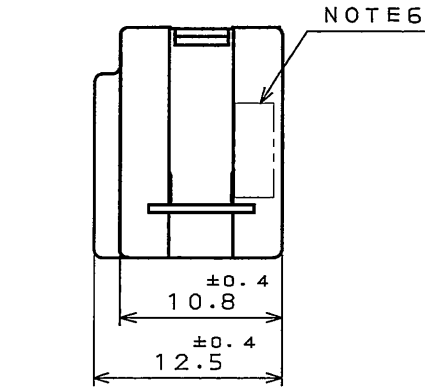
SJ107323

(ON 0NIMVHD)台票圖圖

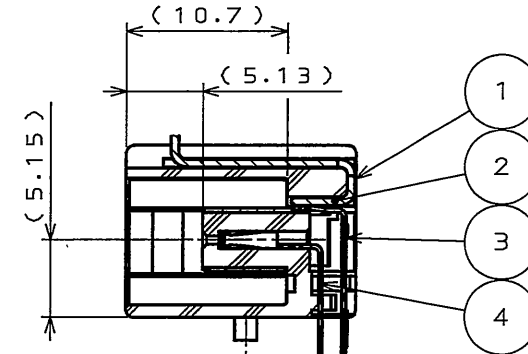
版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.



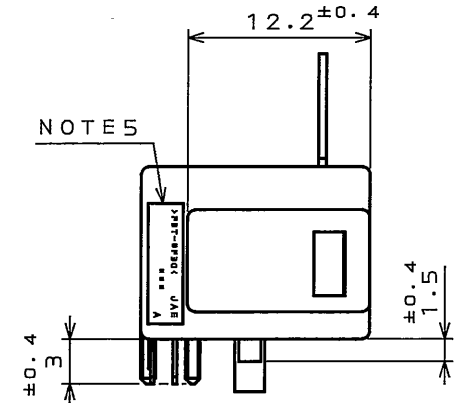
MATED CONDITION (REF.)
嵌合状態図(参考)



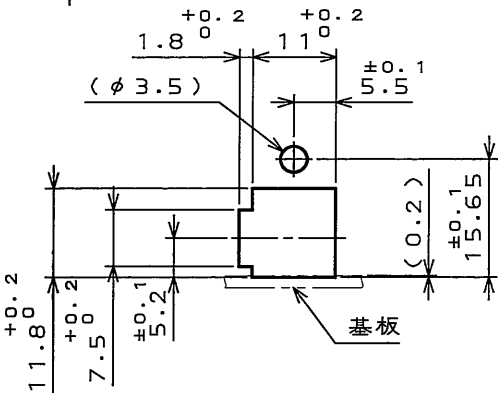
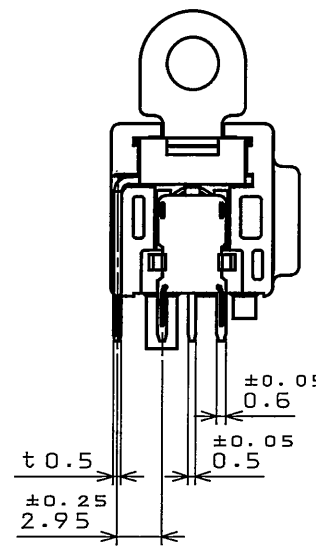
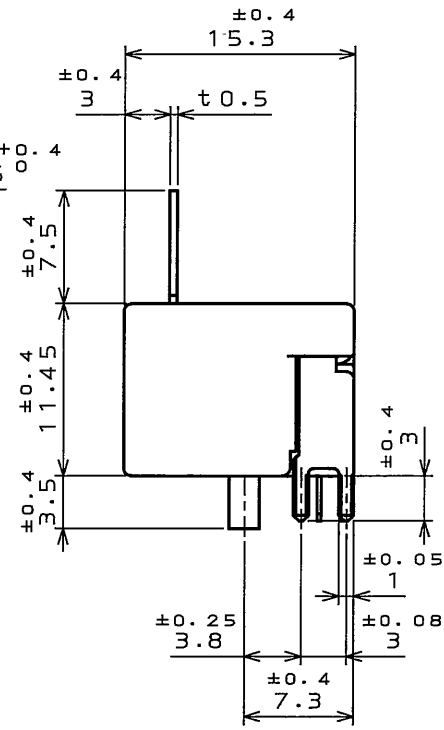
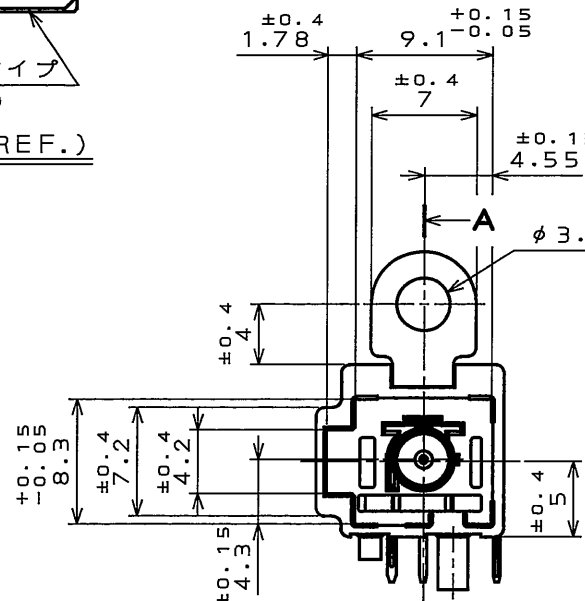
NOTE 6



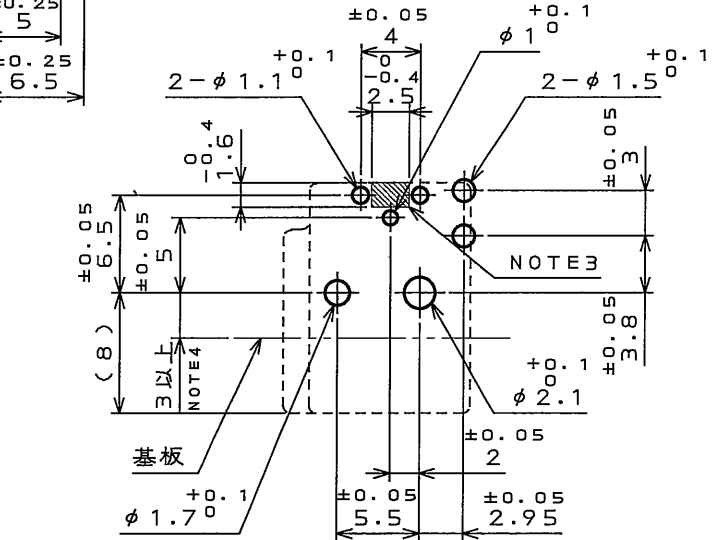
SECT. A-A
(SCALE 5:1)



NOTE 5



PANEL HOLE PATTERNS (REF.)
パネル取付穴寸法(参考)



P.C.B. LAYOUT · MOUNTING SIDE (REF.)
基板取付穴寸法(参考・装着面)

- NOTE 1. APPLICABLE P.C.B THICKNESS : 1.6mm
 2. APPLY THE HEAT TO MELT RIB, SO THAT THE RIB MAY STICK FIRMLY TO P.C.B. WITHOUT LEAVING SPACE BETWEEN THEM.
 3. PATTERN PROHIBITION AREA (CONNECTOR MOUNTING SIDE)
 4. THE DISTANCE SHALL BE MORE THAN 3mm WHEN HEATING TO MELT RIB.
 5. COMPANY LOGO "JAE", MOLD CAVITY DESIGNATOR AND MATERIAL MARKS "PBT-GF30" IS INDICATED AS SHOWN.
 6. THE ASSEMBLY LOT NO. IS INDICATED AS SHOWN.

- 注 1. 適合基板厚 : 1.6mm
 2. 溶着用レグは基板裏側から基板との浮きが無いよう確実に溶着し固定すること。
 3. パターン禁止区域(コネクタ実装面)
 4. レグ溶着時は3mm以上であること。
 5. 図示の位置に社標、金型マーク、材料名の表示を行う。
 6. 図示の位置に組立ロットの表示を行う。

符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
4	INNER TERMINAL	1	COPPER ALLOY	SELECTIVE GOLD PLATING SELECTIVE TIN PLATING	
3	OUTER TERMINAL	1	COPPER ALLOY	TIN PLATING	
2	BRACKET	1	COPPER ALLOY	TIN PLATING	
1	HOUSING	1	GF PBT	(COLOR: LIGHT GRAY)	

仕様書(SPECIFICATION) JACS-20084	第1版(ORIGINAL DATE) 10.May.2007	尺度(SCALE) 2:1	シリーズ(SERIES) CE2	日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD. 図面番号(DRAWING NO.) SJ107323
公差(GENERAL TOLERANCE)	製図 DR.	名称(TITLE) CE2S101C02		
寸法(DIMENSION)	担当 CHK. H.MIZUSHINA	質量(MASS)		
角度(ANGLES)	査閲 APPD. T.MIYASHITA	承認 APPD. Y. Sugii		

DOF-0-212F(05.08)

